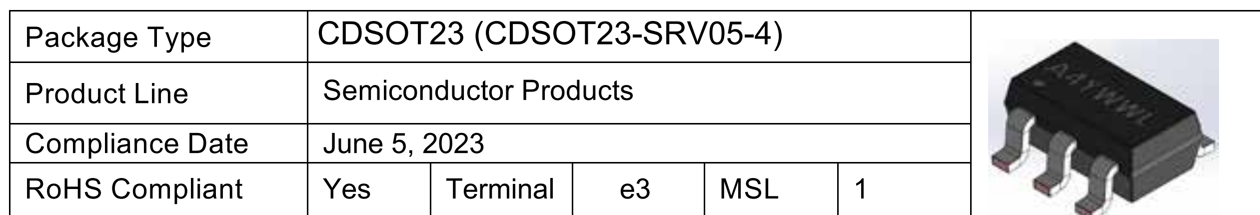
MATERIAL DECLARATION SHEET



Package Type	CDSOT23 (CDSOT23-SRV05-4)				
Product Line	Semiconductor Products				
Compliance Date	June 5, 2023				
RoHS Compliant	Yes	Terminal	e3	MSL	1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy Resin	0.008240	Amorphous Silica	60676-86-0	91.69	45.129	49.219
				Epoxy Resin A	Proprietary	4.17	2.051	
				Epoxy Resin B	29690-82-2	1.41	0.696	
				Phenol Resin	Proprietary	2.15	1.056	
				Carbon Black	1333-86-4	0.58	0.287	
2	Leadframe	Copper Alloy	0.006929	Copper	7440-50-8	97.399	40.306	41.384
				Iron	7439-89-6	2.389	0.989	
				Phosphorus	7723-14-0	0.076	0.032	
				Zinc	7440-66-6	0.127	0.053	
				Lead	7439-92-1	0.009	0.004	
		Silver Plating	0.000007	Silver	7440-22-4	100.00	0.040	0.040
3	Chip	Silicon	0.000676	Silicon	7440-21-3	91.884	3.653	4.035
				Nickel	7440-02-0	6.125	0.243	
				Aluminum	7429-90-5	1.612	0.124	
				Gold	7440-57-5	0.379	0.015	
4	Die Attach	Silver Epoxy	0.000184	Silver	7440-22-4	95.190	1.0481	1.101
				Bisphenol-F-(Epichlorhydrin); Epoxy resin	9003-36-5	2.756	0.0303	
				1,4-Bis(2,3-epoxypropoxy) butane	2425-79-8	1.061	0.0117	
				Aromatic polyamine	Proprietary	0.965	0.0106	
				Adipic Acid	124-04-9	0.028	0.0003	
5	Bond Wires	Copper	0.00006	Copper	7440-50-8	98.260	0.357	0.363
				Non - Cu element	Proprietary	1.740	0.006	
6	Lead Finish	Matte Tin	0.000646	Tin	7440-31-5	100.00	3.858	3.858
		Total Weight	0.016742					

Important remarks:

1. It is responsibility of the user to verify they are accessing the latest version.

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